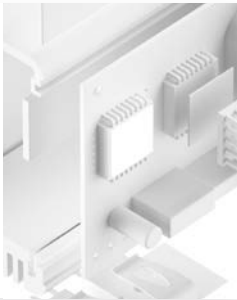


SILICONE-FREE THERMAL GREASE
 TGR-M-NS
 HALA
 highly thermally conductive

TGR-M-NS is high performing silicone-free thermal grease based on an ester oil matrix. It is ideal for use in applications where a very good and highly reliable thermal transfer must be achieved. Due to the specific formulation and filling with ceramic particles the material has a high thermal conductivity. By its use the thermal contact is maximised, hence the total thermal resistance is minimised.



Release 09 / 2026

PROPERTIES

- ☐ Thermal conductivity: 2.4 W/mK
- ☐ Silicone-free
- ☐ Dispensable
- ☐ Almost zero pressure at assembly
- ☐ Dielectric strength
- ☐ Operating temperature range: -40 to 150°C

AVAILABILITY

- ☐ Syringes 70 ml
- ☐ Jars 1 kg

APPLICATION EXAMPLES

Thermal link of:

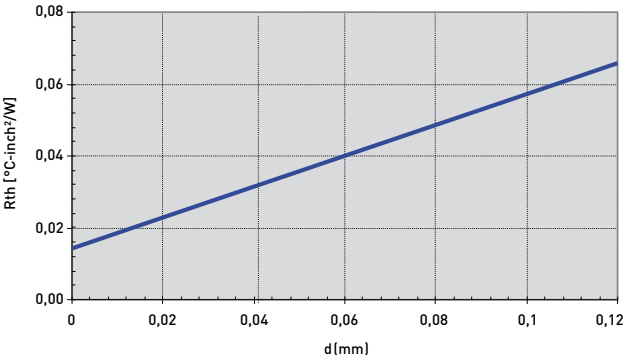
- ☐ LED Boards
- ☐ Power modules
- ☐ RDRAMs memory modules
- ☐ Flip Chips, DSPs , BGAs, PPGAs

For use in Automotive applications / Power electronics / Light technology / Industrial PCs

Technical Data Sheet

PROPERTY	UNIT	TGR-M-NS
MATERIAL		
Colour		White
Density	g /cm³	3.2
Viscosity @ 25°C (Brookfield @ 10 rpm, 25 °C)	Pas	110
RoHS Conformity	2015 / 863 / EU	Yes
THERMAL		
Thermal Conductivity	W/mK	2.4
Operating Temperature Range	°C	- 40 to + 150
Storage Temperature	°C	< 35
Shelf Life (from Date of Manufacturing, unopened)	Months @ RT	12
ELECTRIC		
Dielectric Strength	kV / mm	4.5

Typical, non-binding values. Not intended for specification purposes. Subject to technical changes. Please contact us for further information.



All technical data and information are without warranty and believed to be reliable and accurate corresponding to the latest state of the art. Since the products are not provided to conform with mutually agreed specifications and their use and processing are unknown we cannot guarantee results, freedom from patent infringement, or their suitability for any application. Product testing by the applicant is recommended. We reserve the right of changes.